



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
PATENT APPLICATION

In re Application of:

Tz-Cheng Chiu

Atty. Docket: TI-35061

Serial No.: 10/631,130

Art Unit: 2825

Filed: 07/31/2003

Examiner: C. Lee

For: COMPOSITE LID FOR LAND GRID ARRAY (LGA) FLIP-CHIP
PACKAGE ASSEMBLY

MS PGPUB Drawings
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING 37 CFR §1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450 on the date indicated below.

7-15-04

Jackie McBride
Jackie McBride

LETTER TO THE OFFICIAL DRAFTSPERSON

Sir:

The two attached sheets of drawings include changes to Figures 1A, 1B, and 2. The amended Figures 1A, 1B, and 2 are labeled "Prior Art" as required by the Examiner in the Examiner's Amendment mailed April 23, 2004. The sheet including Figures 1A and 1B replaces the original sheet including Figures 1A and 1B. The sheet including Figure 2 replaces the original sheet including Figure 2.

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Respectfully submitted,

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